● General Description

The AGM612I combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

● Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

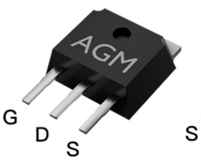
● Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

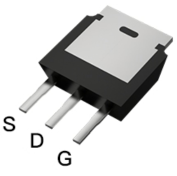
Product Summary

BVDSS	RDSON	ID
60V	11mΩ	50A

TO-251 Pin Configuration

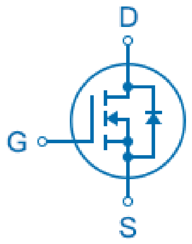


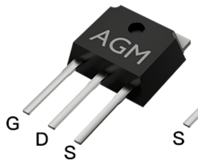
Top View



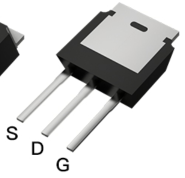
Bottom View

AGM612IS





Top View



Bottom View

AGM612I

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM612I	AGM612I	TO-251	---	---	4500
AGM612IS	AGM612IS	TO-251	---	---	4500

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V）	60	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) **(Note 1)**	50	A
	Drain Current-Continuous(Tc=100℃)	32	A
IDM (pluse)	Drain Current-Pulsed **(Note 2)**	200	A
PD	Maximum Power Dissipation(Tc=25℃)	78	w
	Maximum Power Dissipation(Tc=100℃)	31	w
EAS	Avalanche energy **(Note 3)**	91	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	℃

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State)[1]	---	58	℃/W
RθJC	Thermal Resistance Junction-Case[1]	---	1.6	℃/W

Table 3. Electrical Characteristics (TJ=25℃unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	60	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=60V,VGS=0V	--	--	1.0	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2	1.5	2.2	V
gFS	Forward Transconductance	VDS=5V,ID=6A	--	4	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=10A	--	11	14	mΩ
		VGS=4.5V, ID=6A	--	15	17	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=30V,VGS=0V, F=100 kHz	--	1000	--	pF
Coss	Output Capacitance		--	170	--	pF
Crss	Reverse Transfer Capacitance		--	9.9	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	1.7	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=10V,VDS=15V Rl=0.75Ω,RGEN=3.3Ω	--	25	--	nS
tr	Turn-on Rise Time		--	7.6	--	nS
td(off)	Turn-Off Delay Time		--	34	--	nS
tf	Turn-Off Fall Time		--	6.0	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=20V, ID=12A	--	17	--	nC
Qgs	Gate-Source Charge		--	3.8	--	nC
Qgd	Gate-Drain Charge		--	4.2	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	50	A
VSD	Forward on Voltage	VGS=0V,IS=10A	--	--	1.2	V
trr	Reverse Recovery Time	Is=10A , dI/dt=100A/μ s ,TJ=25℃	--	--	--	ns
Qrr	Reverse Recovery Charge		--	--	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25℃

Electrical Characteristics Diagrams

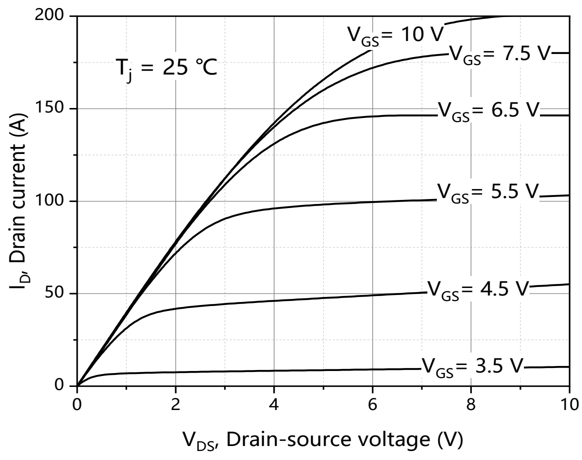


Figure 1. Typ. output characteristics

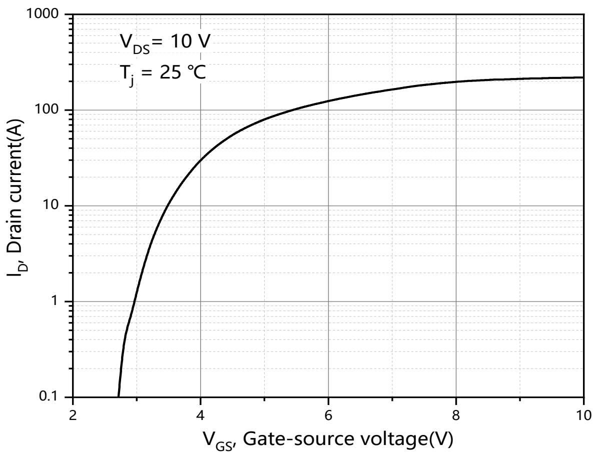


Figure 2. Typ. transfer characteristics

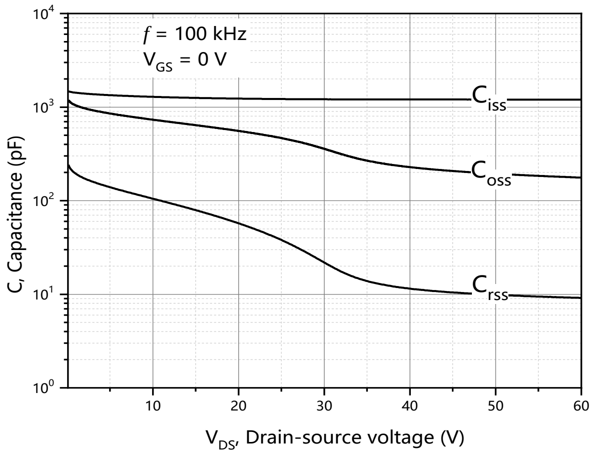


Figure 3. Typ. capacitances

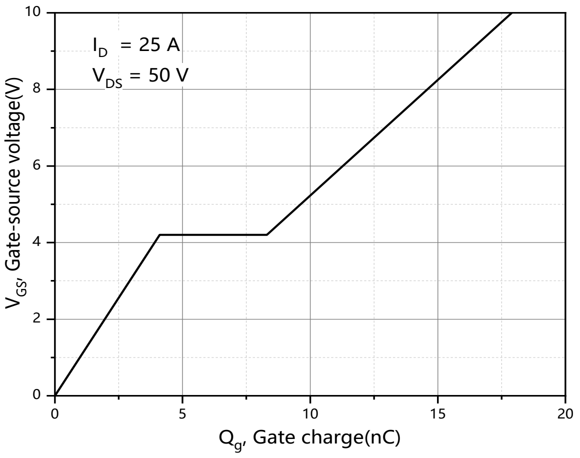


Figure 4. Typ. gate charge

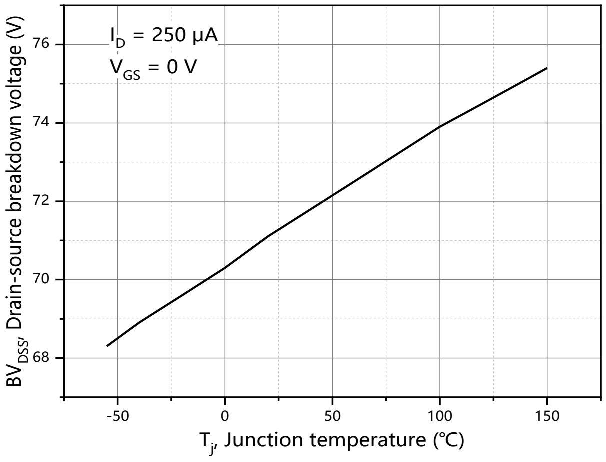


Figure 5. Drain-source breakdown voltage

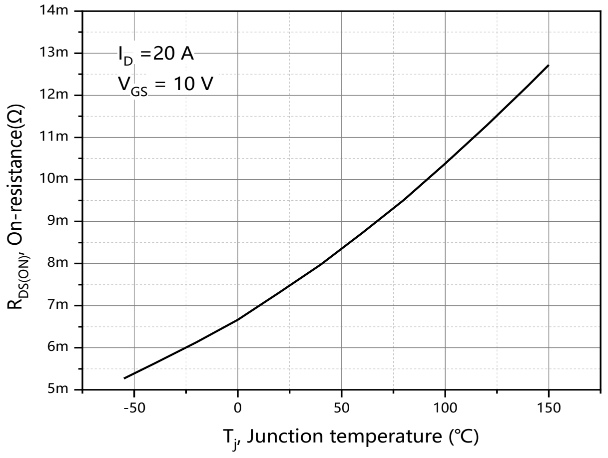


Figure 6. Drain-source on-state resistance

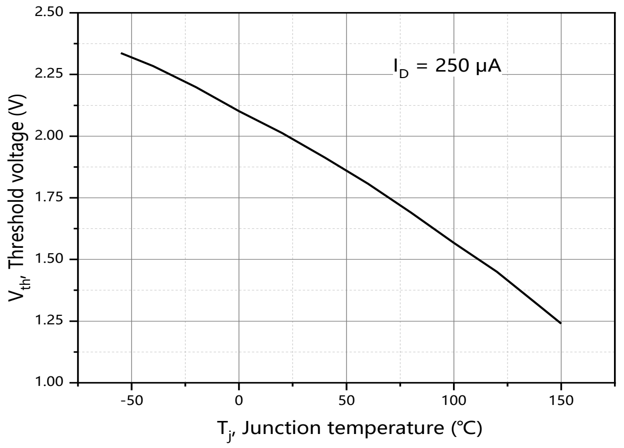


Figure 7. Threshold voltage

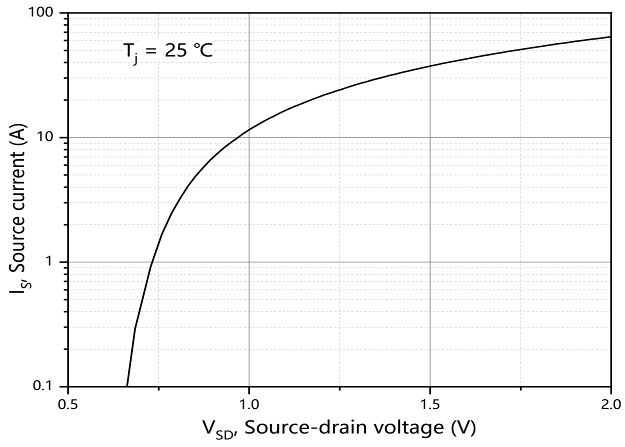


Figure 8. Forward characteristic of body diode

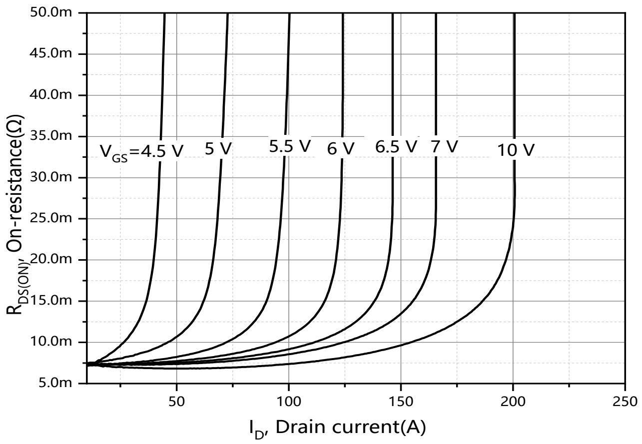


Figure 9. Drain-source on-state resistance

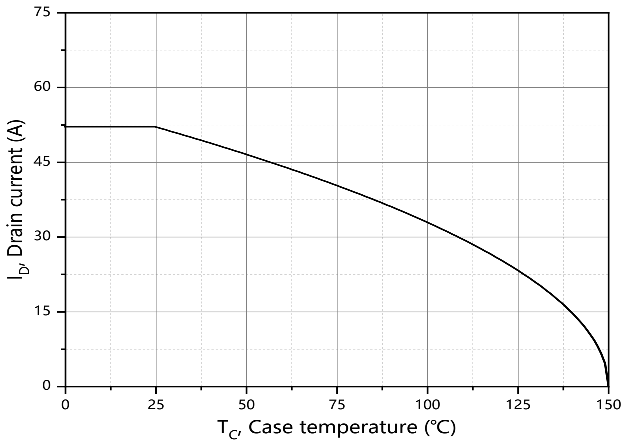


Figure 10. Drain current

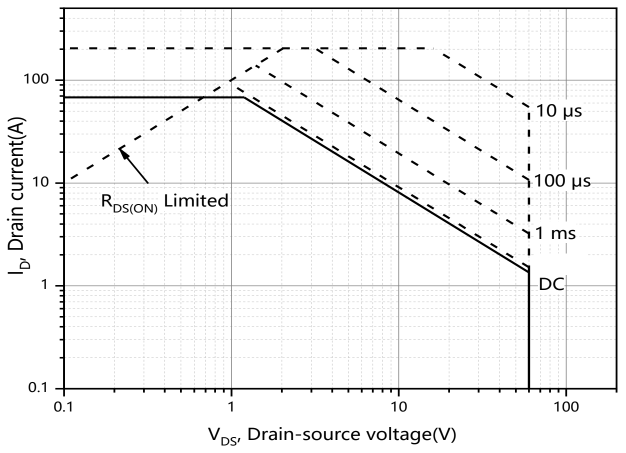


Figure 11. Safe operation area TC=25 ℃

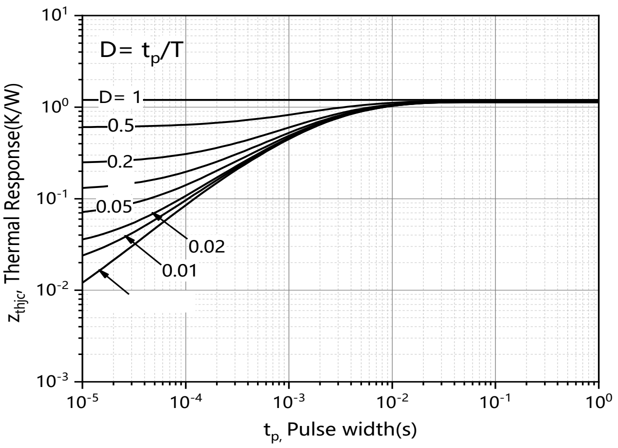


Figure 12. Max. transient thermal impedance

Test circuits and waveforms

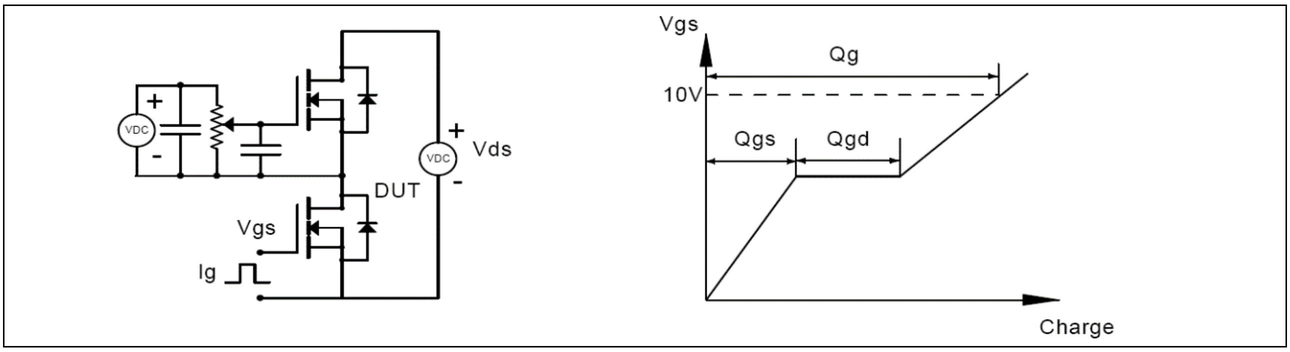


Figure 1. Gate charge test circuit & waveform

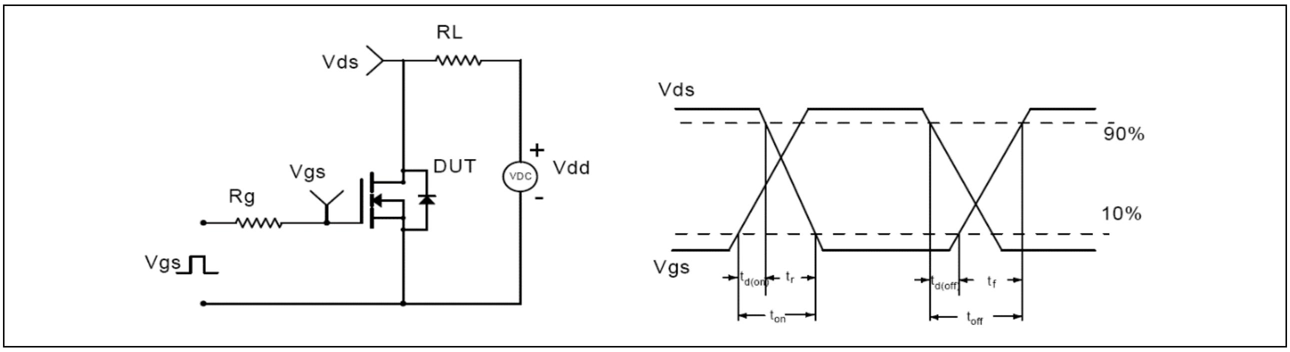


Figure 2. Switching time test circuit & waveforms

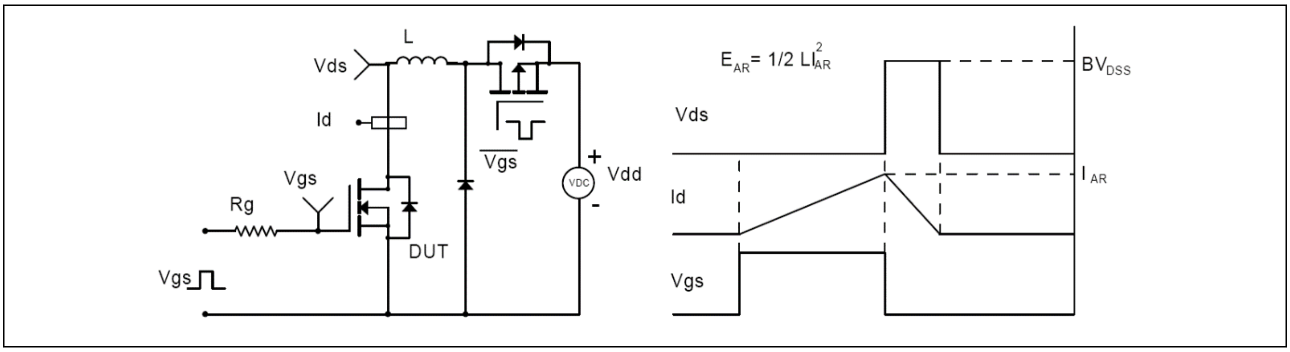


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

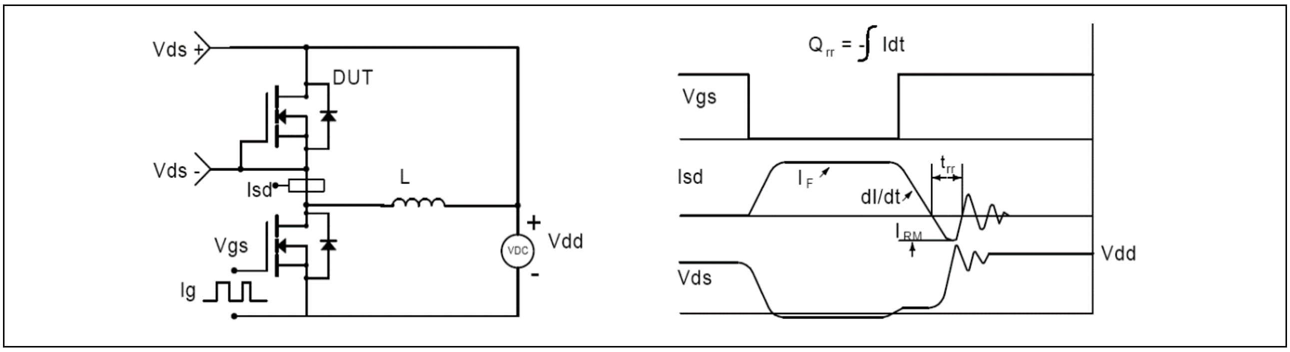
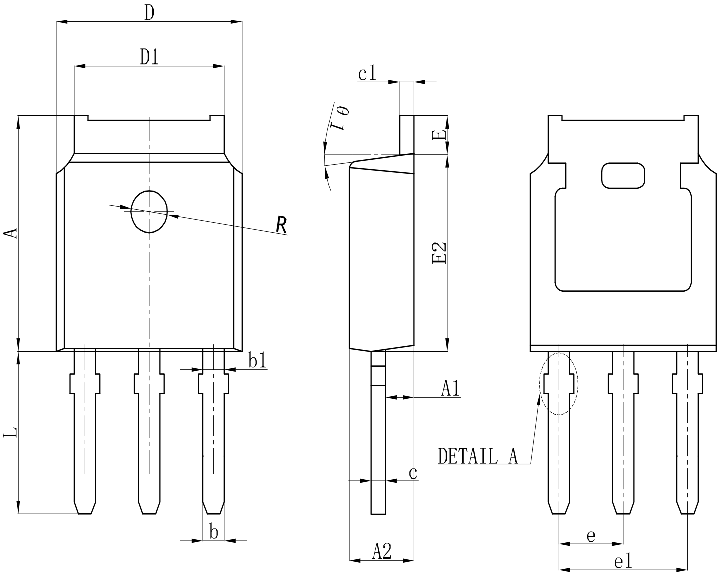
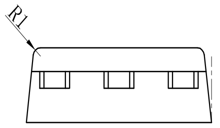


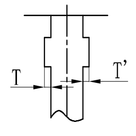
Figure 4. Diode reverse recovery test circuit & waveforms

TO-251 Package Outline Data

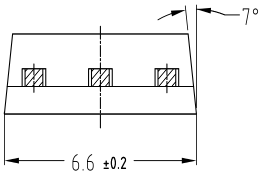


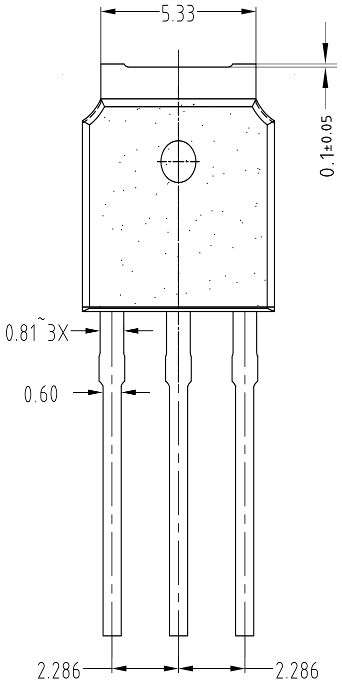
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	7.050	7.100	7.150
A1	0.960	1.010	1.060
A2	2.250	2.300	2.350
b	0.760REF.		
b1	1.000REF.		
c	0.508REF.		
c1	0.508REF.		
D	6.550	6.600	6.650
D1	5.220	5.320	5.420
E	0.950	1.000	1.050
E2	6.050	6.100	6.150
e	2.286BSC		
e1	4.572REF.		
L	4.800	5.000	5.200
θ1	7° REF.		
R	1.300REF.		
R1	0.250REF.		

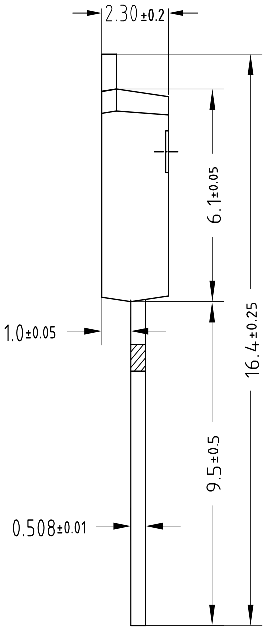




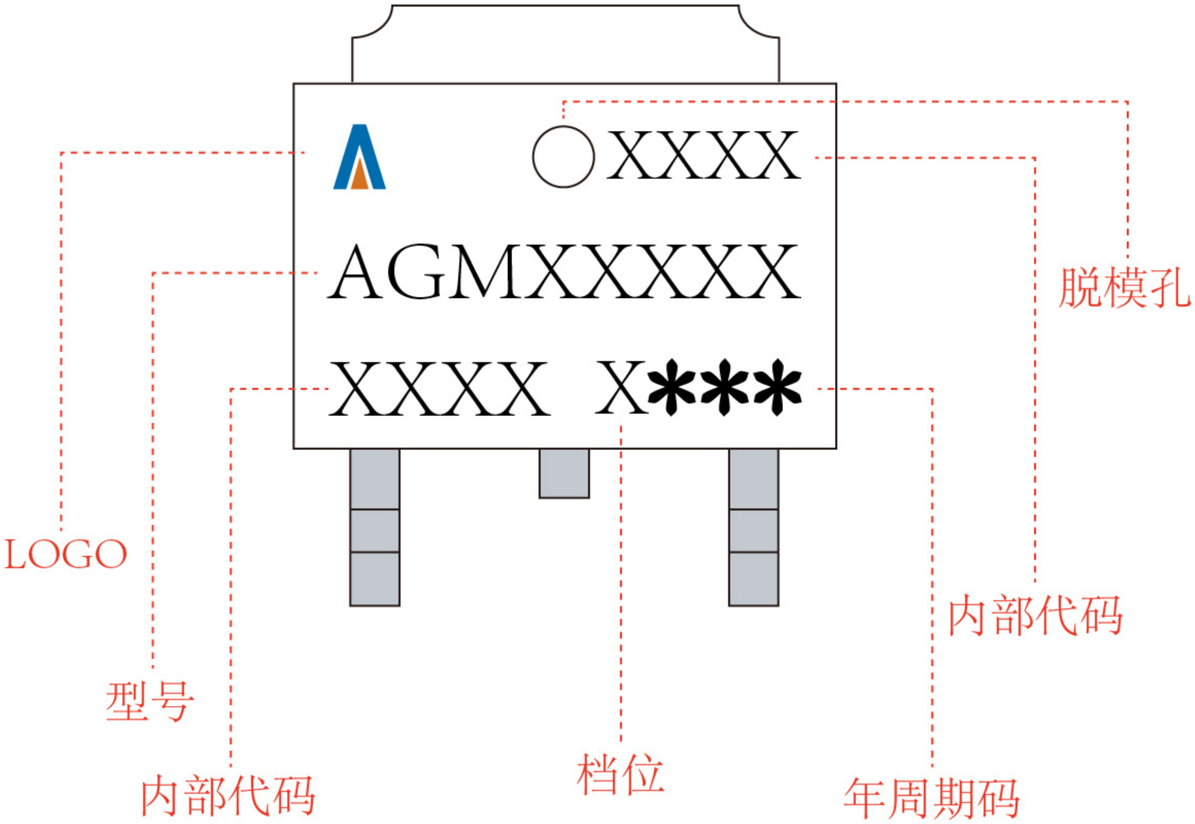
0<=T, T'<=0.1
DETAIL A







TO-251
Marking Instructions:



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